Safety
- The FlexAL ALD tool uses toxic and highly reactive/pyrophoric precursors for film deposition. Materials are monitored by the Toxic Gas Monitoring and Control System that will sound a gas alarm in the event of a detection.

Process Restrictions
Material Restrictions
- Full size 100mm wafers (other wafer sizes up to 200mm can be accommodated with staff assistance).
- Pieces can be processed with the use of a carrier wafer or plate.
- Polymers and resist need to be fully cured and only run at process temperatures below 150 C.

Parameter Restrictions
- None

Scheduling / Sign-up Restrictions
- None

Requirements (Do Every Time)
- Indicate film type(s) deposited and number of loops during the CORAL log out process.

Prohibitions (Never Do)
- None

Common Problems
Problem: Root Cause: Solution:

Other Comments or Cautions